

Board File Name: blufi\_poe.PcbDoc  
Design Name: blWifi\_poe

Hole Count: 894  
Via Count: 841  
Pad Count: 1034

Board Material: FR408  
Number of Layers: 4  
Copper Weight: 1 Oz  
Finished Board Thickness: 0.8 mm  
Min Trace: 5mil  
Min Space: 4mil

Soldermask Type: LPI/BLUE  
Pad finish: ENIG  
Silkscreen Color: WHITE

Minimum Via Size: Drill 10mil Dia 20mil

Files:

- Top Layer: GTL
- Top Soldermask: GTS
- Top Paste: GTP
- Top Silkscreen: GTO
- Signal 1: G1
- Signal 2: G2
- Bottom Layer: GBL
- Bottom Soldermask: GBS
- Bottom Paste: GBP
- Bottom Silkscreen: GBO

Board Outline: GM1 cut according to this layer

Drill: TXT Top-Bottom

Documentation:

PDF

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric 3	FR408	16.00mil	4.03	
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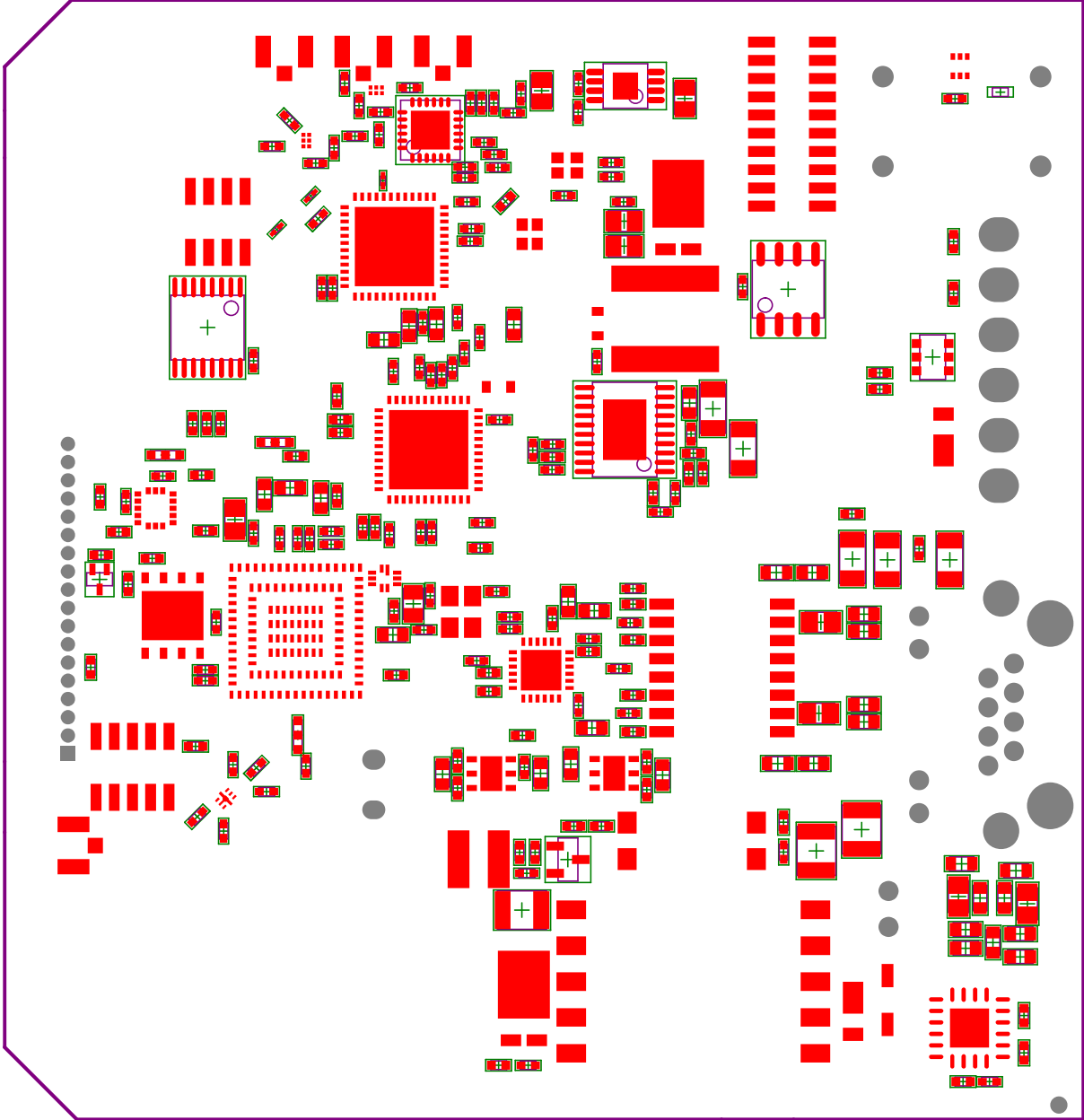
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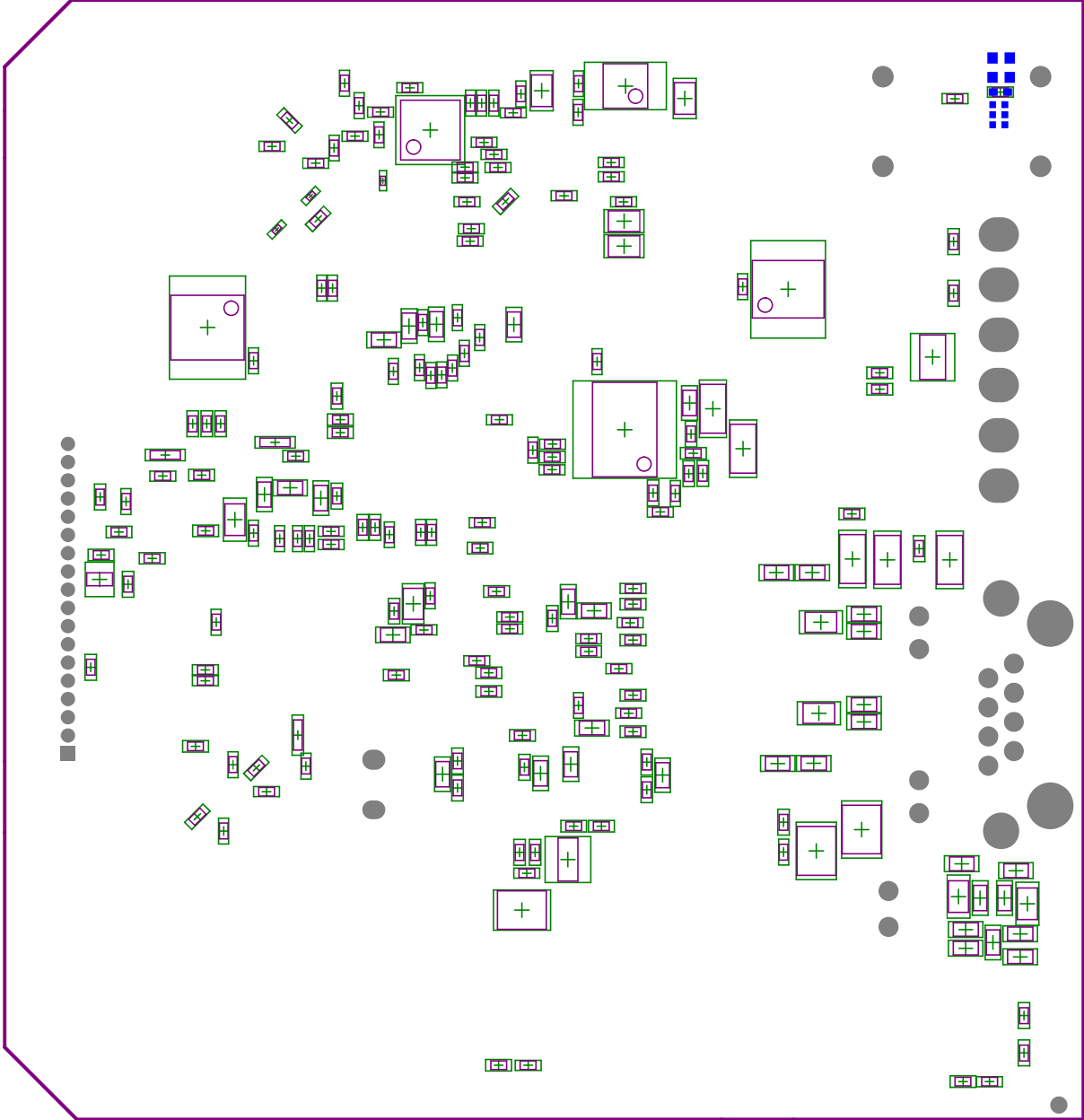
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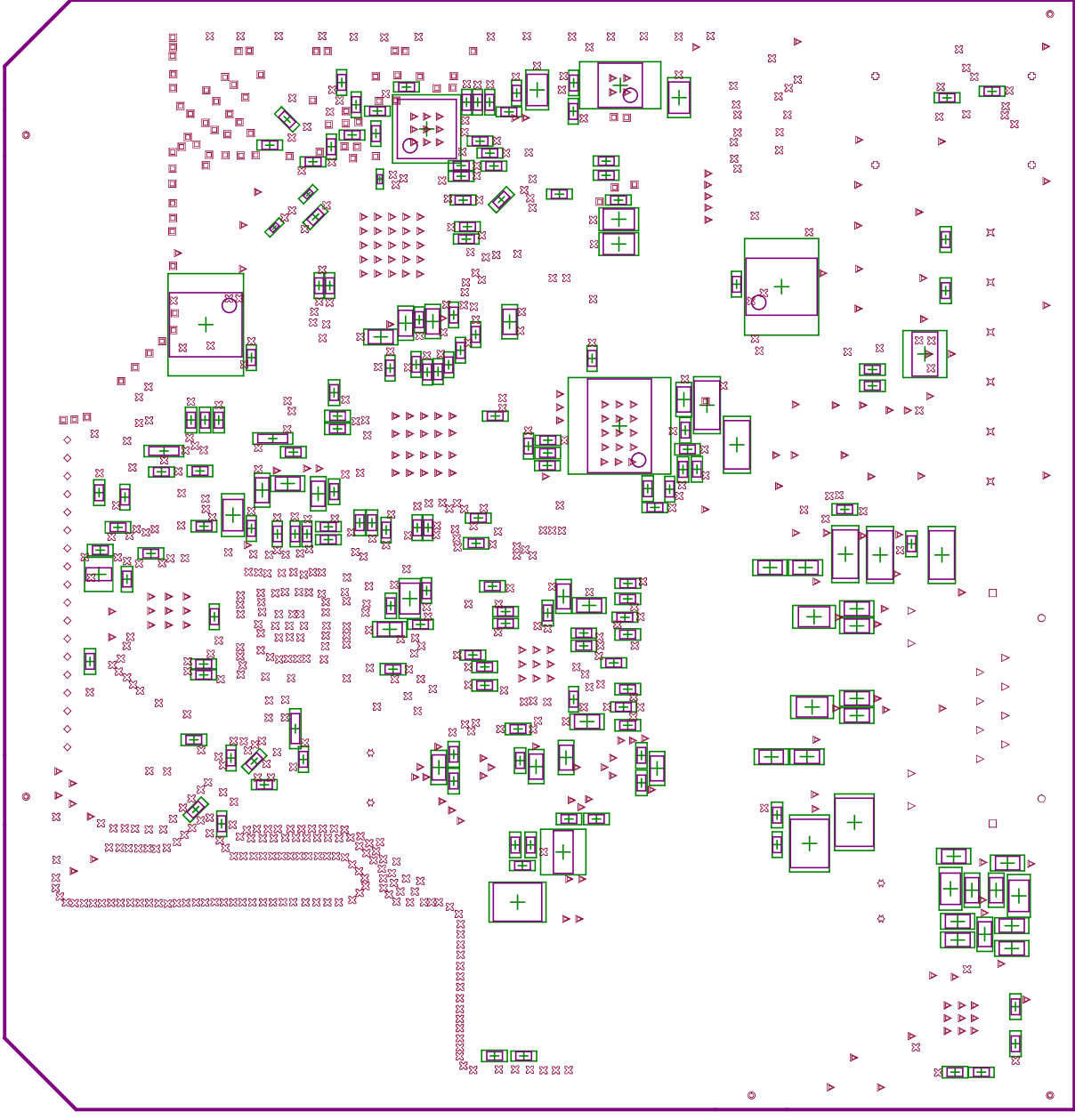
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Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
⊗	550	0.25mm	PTH	Round	Top Layer- Bottom Layer	Via	Rounded	(Mixed)
⬇	75	0.305mm	PTH	Round	Top Layer- Bottom Layer	Via	Rounded	v61h30m0m0
⬆	216	0.356mm	PTH	Round	Top Layer- Bottom Layer	Via	Rounded	(Mixed)
⬇	18	0.600mm	PTH	Round	Top Layer- Bottom Layer	Pad	(Mixed)	(Mixed)
⬆	4	0.700mm	PTH	Round	Top Layer- Bottom Layer	Pad	Rounded	(Mixed)
⬇	12	0.889mm	PTH	Round	Top Layer- Bottom Layer	Pad	Rounded	c:10h89
⬆	4	1.000mm	PTH	Round	Top Layer- Bottom Layer	Pad	Rounded	r150_150h100r100
⬇	5	1.200mm	NPTH	Round	Top Layer- Bottom Layer	Pad	Rounded	(Mixed)
⬆	6	1.500mm	PTH	Round	Top Layer- Bottom Layer	Pad	Rounded	r240_280h150r100
⬇	2	1.575mm	PTH	Round	Top Layer- Bottom Layer	Pad	Rounded	c254h157
⬆	2	3.25mm	PTH	Round	Top Layer- Bottom Layer	Pad	Rounded	c325h325
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